

MA2C859 (MA859)

Silicon epitaxial planar type

For band switching

■ Features

- Extra-small DHD envelope, allowing to insert into a 5 mm pitch hole
- Less voltage dependence of the diode capacitance C_D
- Low forward dynamic resistance r_f
- Optimum for a band switching of tuner

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	35	V
Forward current	I_F	100	mA
Operating ambient temperature*	T_{opr}	-25 to +85	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +100	$^\circ\text{C}$

Note) *: Maximum ambient temperature during operation.

■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_F	$I_F = 100\text{ mA}$			1.0	V
Reverse current* ¹	I_R	$V_R = 33\text{ V}$			100	nA
Diode capacitance	C_D	$V_R = 6\text{ V}, f = 1\text{ MHz}$		0.8	1.2	pF
Forward dynamic resistance* ²	r_f	$I_F = 2\text{ mA}, f = 100\text{ MHz}$		0.77	0.98	Ω

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

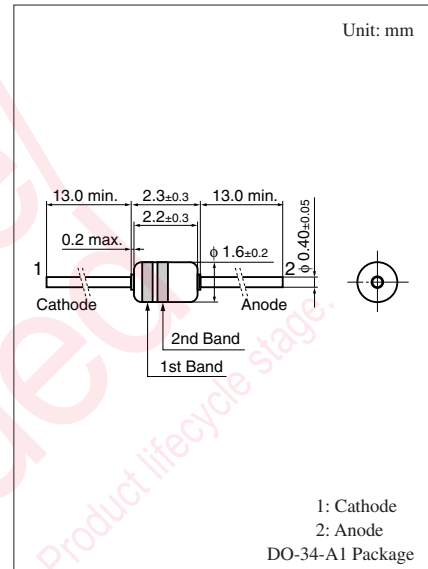
2. Absolute frequency of input and output is 100 MHz.

3. *1: I_R should be measured under the condition of prevention the light.

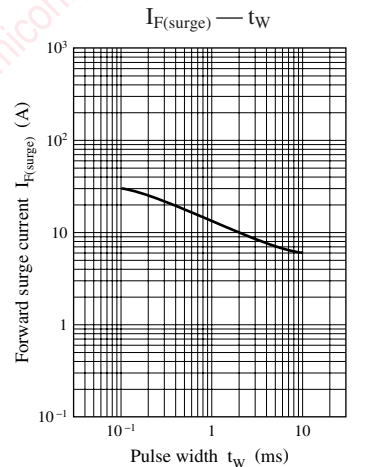
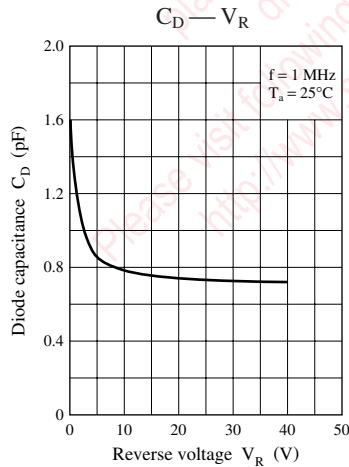
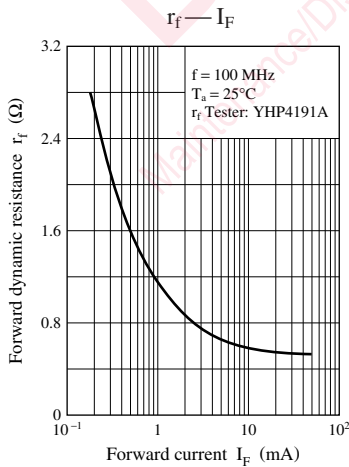
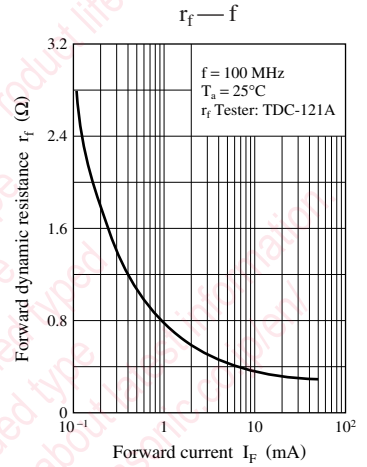
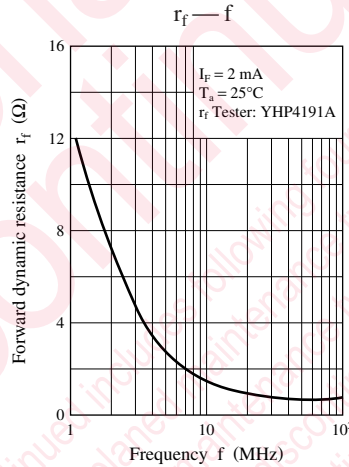
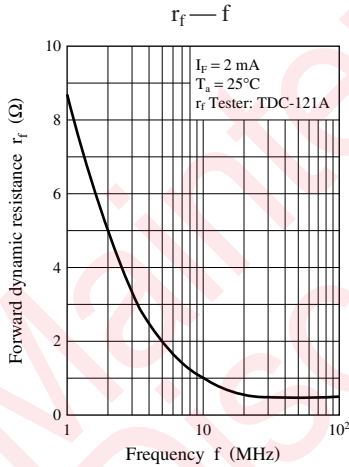
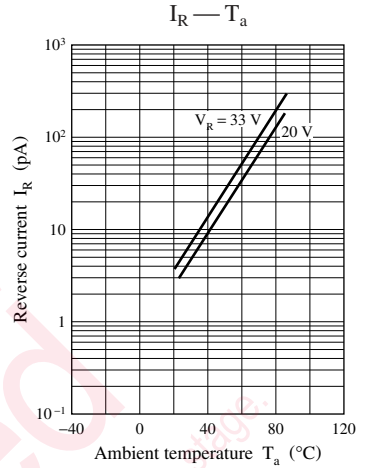
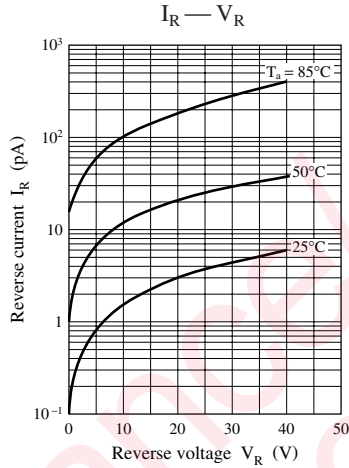
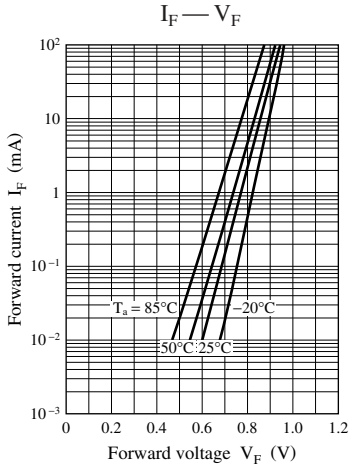
*2: Measuring instrument; YHP MODEL 4191A RF IMPEDANCE ANALYZER

■ Cathode Mark

Type No.		MA2C859
Color	1st Band	Black
	2nd Band	Blue



Note) The part number in the parenthesis shows conventional part number.



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